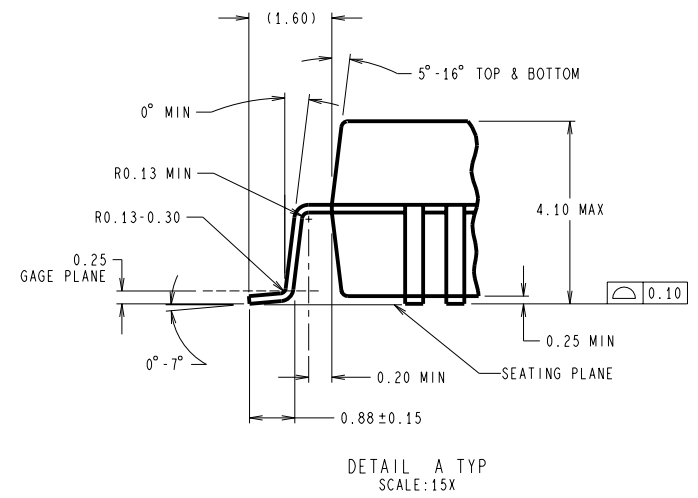
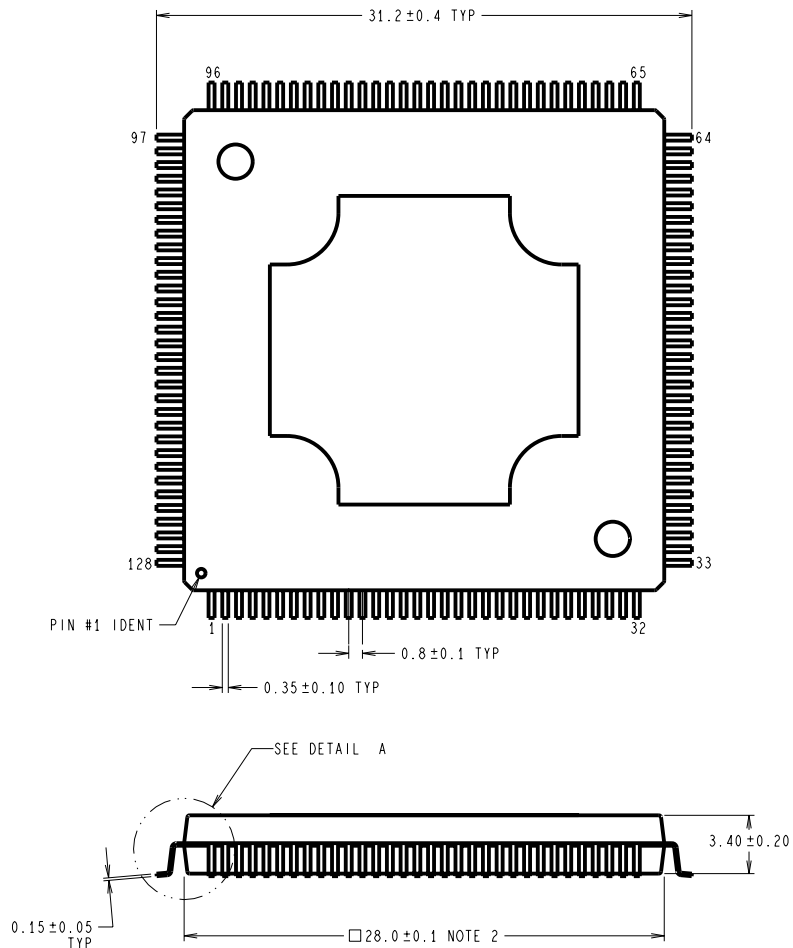


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10357	03/29/94	DEG/HJK
B	REV NOTE 4; 3.40 TOL WAS 0.02; 0°-7° WAS 0°-10°; 0.20 MIN WAS 0.40 MIN	10990	06/06/95	TL/



NOTES: UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN MILLIMETERS

- STANDARD LEAD FINISH:  
5.08 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- CAVITY UP PACKAGE WILL NOT SHOW 2 EJECTOR PIN MARKS BUT  
THE PACKAGE WHICH HAS EXPOSED HEAT SPREADER (OR CAVITY DOWN  
FIGURE) WILL SHOW PIN #1 AND TWO EJECTOR PIN MARKS ON TOP  
OF THE PACKAGE SURFACE.
- REFERENCE JEDEC REGISTRATION MS-022, VARIATION DB-1.  
DATED FEB 1995.

<b>APPROVALS</b>		<b>DATE</b>	<b>NATIONAL SEMICONDUCTOR CORPORATION</b>		
DRN	<i>D. E. Grady</i>	03/29/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.			<b>POFP, JEDEC METRIC, (S), 28 X 28 X 3.4mm, 128 LEAD</b>		
ENGR. CHK.					
APPROVAL					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VOC128A	B
DO NOT SCALE DRAWING					SHEET 1 of 1